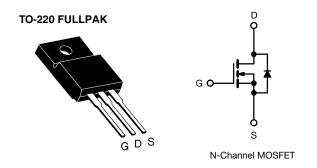


E Series Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.082		
Q _g max. (nC)	132			
Q _{gs} (nC)	22			
Q _{gd} (nC)	46			
Configuration	Single			



FEATURES

• A specific on resistance (m Ω -cm 2) reduction of 25 %



COMPLIANT

HALOGEN

FREE

- \bullet Low figure-of-merit (FOM) $R_{on}\:x\:Q_g$
- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- Power factor correction power supplies (PFC)
- · Hard switching PWM stages
- Computing
 - Switch mode power supplies (SMPS)
- Lighting
 - Light emitting diode (LED)
 - High intensity discharge (HID)
- Telecom
 - Server power supplies
- · Renewable energy
 - Photovoltaic inverters
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Uniterruptable power supplies

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free and Halogen-free	SiHF35N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	600	V	
Gate-Source Voltage			V_{GS}	± 30	v	
Continuous Drain Current (T _J = 150 °C) e	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	- I _D	32		
		T _C = 100 °C		20	Α	
Pulsed Drain Current ^a	ed Drain Current ^a			80		
Linear Derating Factor				0.31	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	691	mJ	
Maximum Power Dissipation			P_{D}	39	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		57	1//		
Reverse Diode dV/dt ^d			dV/dt	31	- V/ns	
Soldering Recommendations (Peak temperature) ^c	For 10 s			300	°C	
Mounting Torque	M3 screw			0.6	Nm	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. $V_{DD} = 140 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 28.2 \, \text{mH}$, $R_g = 25 \, \Omega$, $I_{AS} = 7 \, \text{A}$.
- c. 1.6 mm from case.

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- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.
- e. Limited by maximum junction temperature.



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	=	65	°C/W	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.2	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							•
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2	-	4	V
	I _{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-Source Leakage			V _{GS} = ± 30 V	-	-	± 1	μΑ
Zana Oala Vallana Buria Oanad		V _{DS} =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	25	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 17 A	-	0.082	0.094	Ω
Forward Transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 17 A		-	13	-	S
Dynamic						•	
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1 MHz		-	2760	-	pF
Output Capacitance	C _{oss}			-	118	-	
Reverse Transfer Capacitance	C _{rss}			-	5	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{DS} = 0 V \text{ to } 480 V, V_{GS} = 0 V$		-	118	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	429	-	
Total Gate Charge	Qg			-	88	132	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 17 \text{ A}, V_{DS} = 480 \text{ V}$		22	-	nC
Gate-Drain Charge	Q _{gd}			-	46	-	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 480 V, I _D = 17 A,		=	29	58	
Rise Time	t _r			-	61	92	
Turn-Off Delay Time	t _{d(off)}		$V_{DD} = 480 \text{ V}, T_{D} = 17 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		78	117	ns
Fall Time	t _f			-	32	64	
Gate Input Resistance	R _g	f = 1 MHz, open drain		0.25	0.5	1	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	32	
Pulsed Diode Forward Current	I _{SM}			-	-	80	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 17 \text{ A},$ $dI/dt = 100 \text{ A/µs}, V_R = 25 \text{ V}$		_	455	910	ns
Reverse Recovery Charge	Q _{rr}			-	8	16	μC
Reverse Recovery Current	I _{RRM}			-	30	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

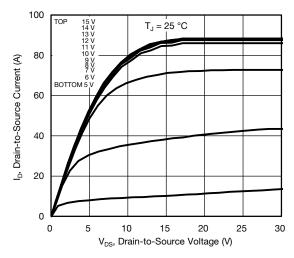


Fig. 1 - Typical Output Characteristics

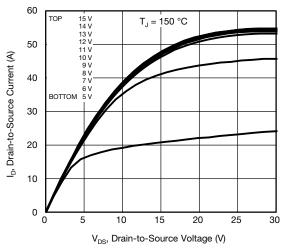


Fig. 2 - Typical Output Characteristics

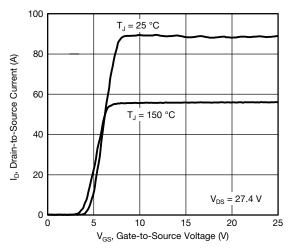


Fig. 3 - Typical Transfer Characteristics

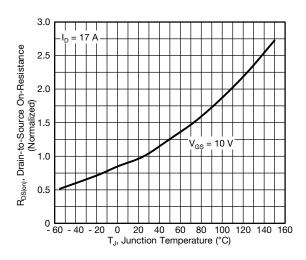


Fig. 4 - Normalized On-Resistance vs. Temperature

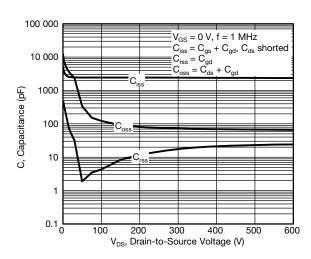


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

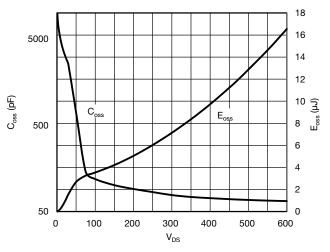


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



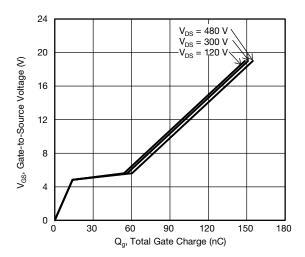


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

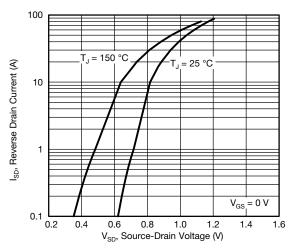


Fig. 8 - Typical Source-Drain Diode Forward Voltage

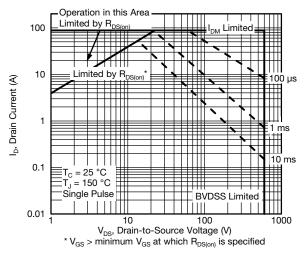


Fig. 9 - Maximum Safe Operating Area

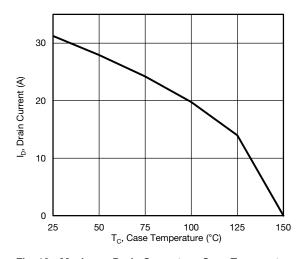


Fig. 10 - Maximum Drain Current vs. Case Temperature

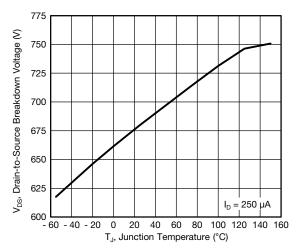


Fig. 11 - Temperature vs. Drain-to-Source Voltage



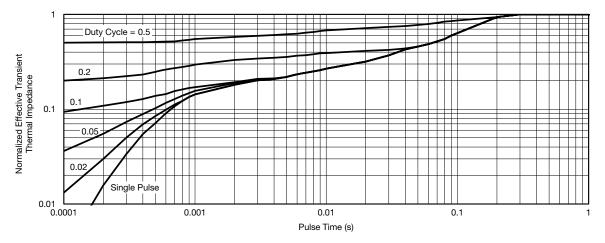


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

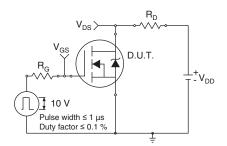


Fig. 13 - Switching Time Test Circuit

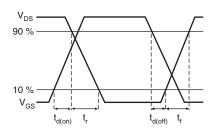


Fig. 14 - Switching Time Waveforms

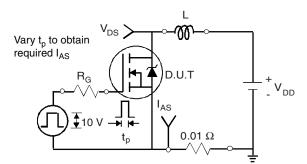


Fig. 15 - Unclamped Inductive Test Circuit

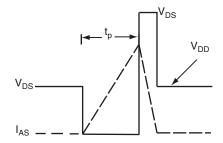


Fig. 16 - Unclamped Inductive Waveforms

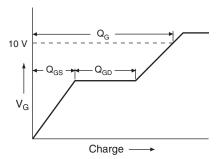


Fig. 17 - Basic Gate Charge Waveform

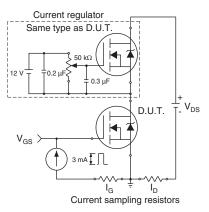
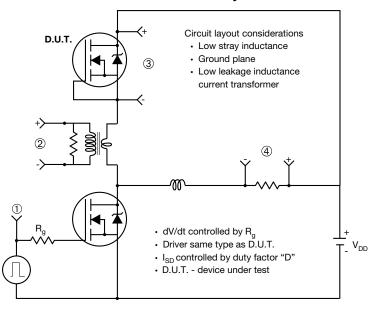


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



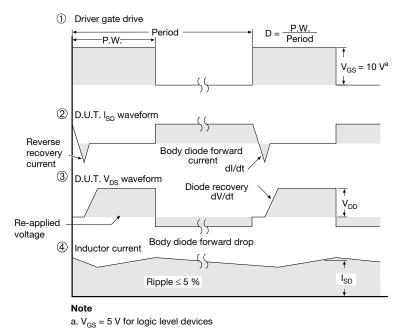


Fig. 19 - For N-Channel

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